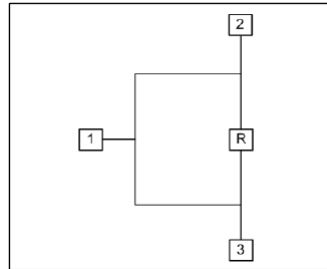


**Features**

- Frequency: 1-18GHz
- Insertion Loss: 1.5dB
- Input/Output: 50Ω matched
- Die Size: 3.2 x 2.5 x 0.1 mm

**Functional Block Diagram**

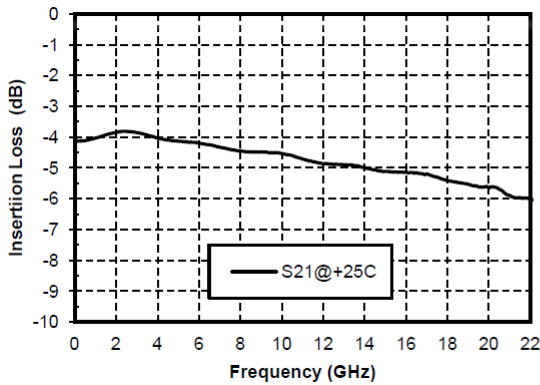


**Electrical Specifications**

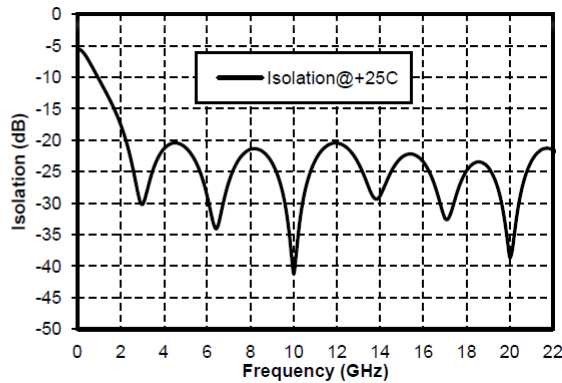
TA = +25°C

Parameters	Min.	Typ.	Max.	Units
Frequency	1-18			GHz
Insertion Loss	0.8	1.5	2.4	dB
Flatness		±0.8		dB
Isolation	11	22		dB
Input Return Loss	14	20		dB
Output Return Loss	16	22		dB

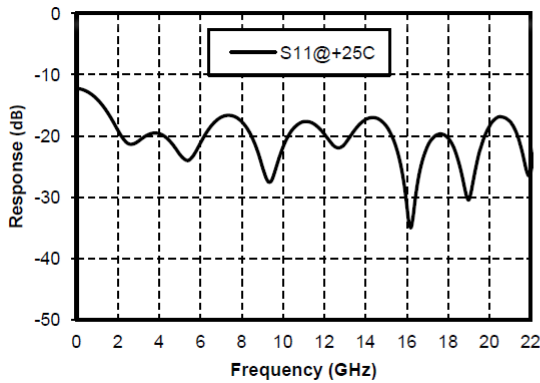
**Insertion Loss**



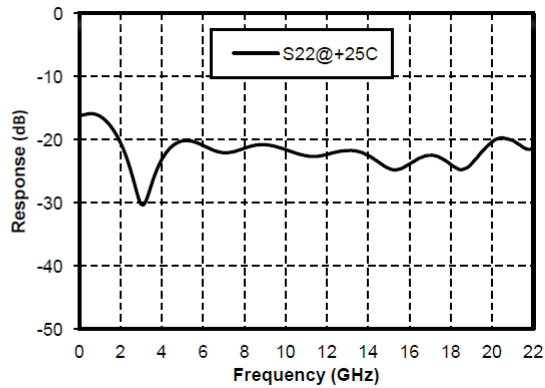
**Isolation**



**Input Return Loss**

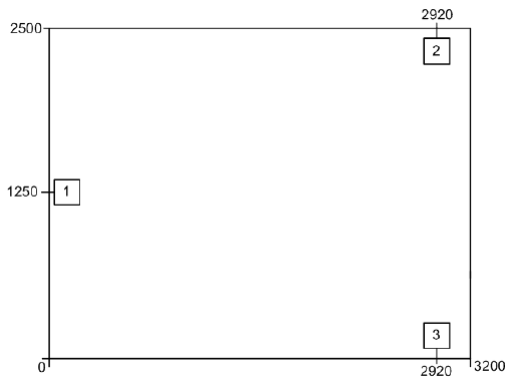


**Output Return Loss**

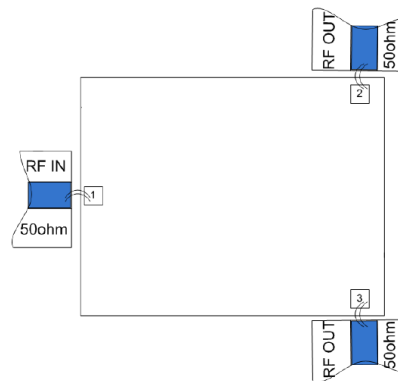


**Outline Drawing**

All Dimensions in um



**Assembly Drawing**



**Pad Description**

Pad	Function	Description
1	RF IN	RF Input Port
2,3	RF OUT	RF Output Port
Die bottom	GND	Die bottom must be connected to RF/DC ground.

**Maximum Ratings:**

1. Maximum input power: +40dBm
2. Operating temperature: -55°C to +85°C
3. Storage temperature: -65°C to +150°C